ABSTRACT

AN APPARATUS AND METHOD FOR DICING AN IC SUBSTRATE

An apparatus (5) for dicing an integrated circuit substrate having a loader (30) for loading the substrate to the apparatus, said substrate loaded in a first direction corresponding to a loading axis, an inlet rail (35) said inlet rail including a first block (75) movable along said inlet rail (35) to which is loaded the substrate from said loader, wherein said inlet rail is arranged to deliver the first block (75) and substrate towards a chuck table (60) in a second direction orthogonal to the loading axis.

Figure 1

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